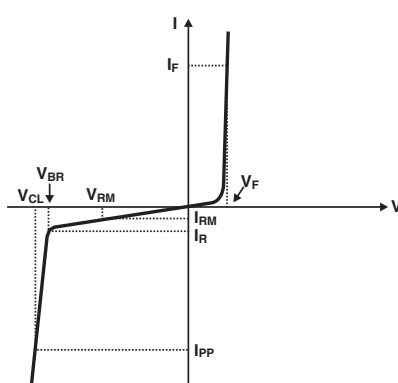


1 Characteristics

Table 1. Absolute ratings (limiting values at $T_{amb} = 25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Unit
V_{PP}	ESD IEC 61000-4-2 air discharge on input pins	15	kV
	ESD IEC 61000-4-2 contact discharge on input pins	8	
	ESD IEC 61000-4-2 contact discharge on output pins	4	
T_j	Junction temperature	125	$^{\circ}\text{C}$
T_{op}	Operating temperature range	-40 to + 85	$^{\circ}\text{C}$
T_{stg}	Storage temperature range	-55 to +150	$^{\circ}\text{C}$

Table 2. Electrical characteristics ($T_{amb} = 25^{\circ}\text{C}$)

Symbol	Parameter	
V_BR	Breakdown voltage	
I_RM	Leakage current @ V_RM	
V_RM	Stand-off voltage	
V_CL	Clamping voltage	
R_d	Dynamic resistance	
I_PP	Peak pulse current	
R_I/O	Series resistance between Input & Output	
C_line	Input capacitance per line	

Symbol	Test conditions	Min.	Typ.	Max.	Unit
V_BR	I_R = 1 mA	6	8	10	V
I_RM	V_RM = 3 V per line			100	nA
R_I/O	Tolerance ± 10%	153	170	187	Ω
C_line	V_LINE = 2.5 V dc, V_OSC = 30 mV, F = 1 MHz	12	14	16.5	pF

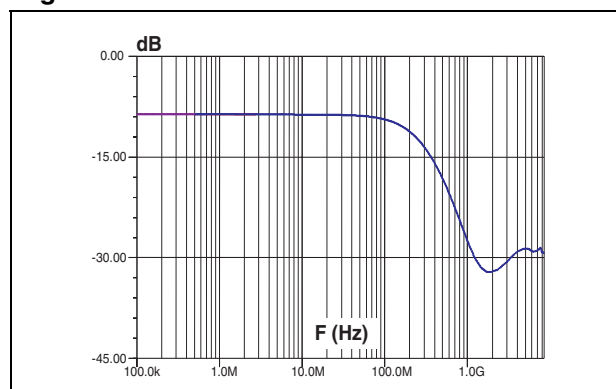
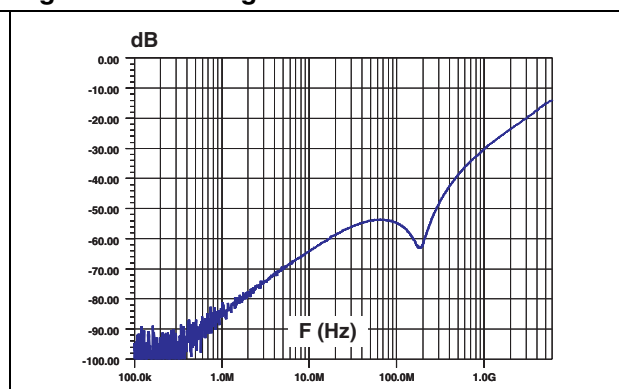
Figure 3. S21 attenuation measurement

Figure 4. Analog cross talk measurements


Figure 5. ESD response to IEC 61000-4-2 (+15 kV air discharge) on one input (V_{in}) and on one output (V_{out})

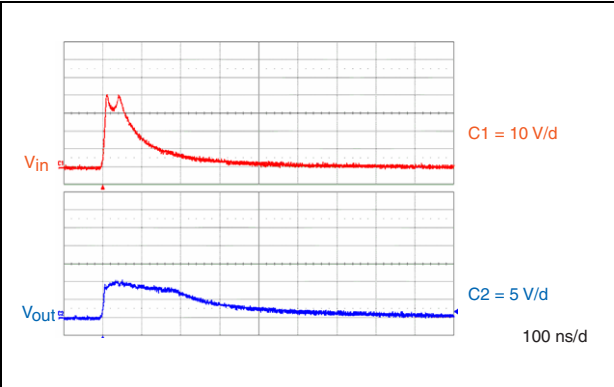


Figure 6. ESD response to IEC 61000-4-2 (- 15 kV air discharge) on one input (V_{in}) and on one output (V_{out})

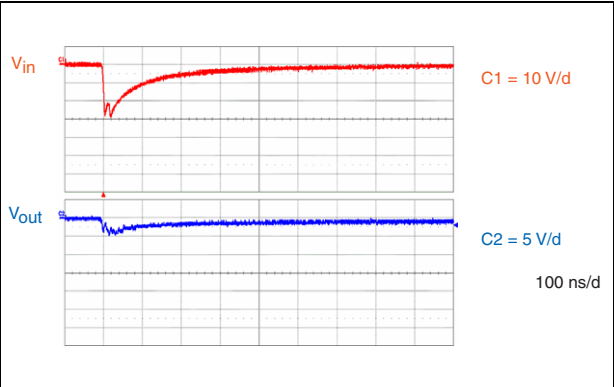
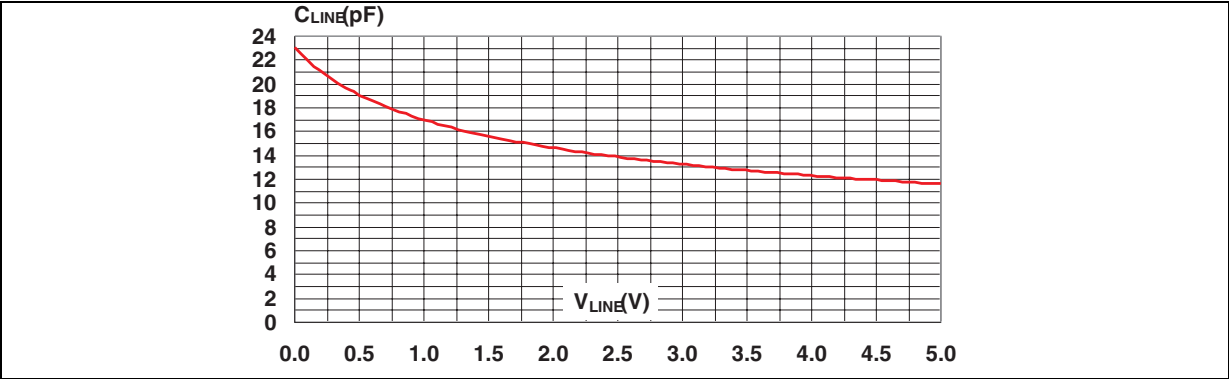
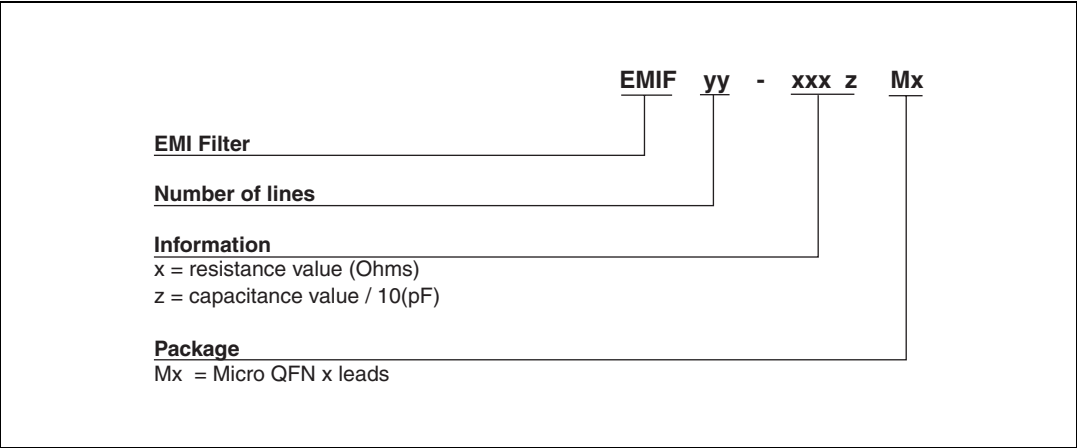


Figure 7. Line capacitance versus reverse voltage applied (typical value)



2 Ordering information scheme

Figure 8. Ordering information scheme



3 Package information

- Epoxy meets UL94, V0

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

Table 3. QFN 1.7 x 1.5 package dimensions

Ref	Dimensions					
	Millimeters			inches		
	MIN	TYP	MAX	MIN	TYP	MAX
A	0.50	0.55	0.60	0.20	0.22	0.24
A1	0.00	0.02	0.05	0.00	0.01	0.02
b	0.15	0.18	0.25	0.06	0.07	0.10
D		1.70			0.67	
D2	0.9	1.00	1.10	0.35	0.39	0.43
E		1.50			0.59	
E2	0.30	0.40	0.50	0.12	0.16	0.24
e		0.40			0.16	
k	0.20			0.08		
L	0.25	0.30	0.35	0.10	0.12	0.14

Figure 9. Footprint

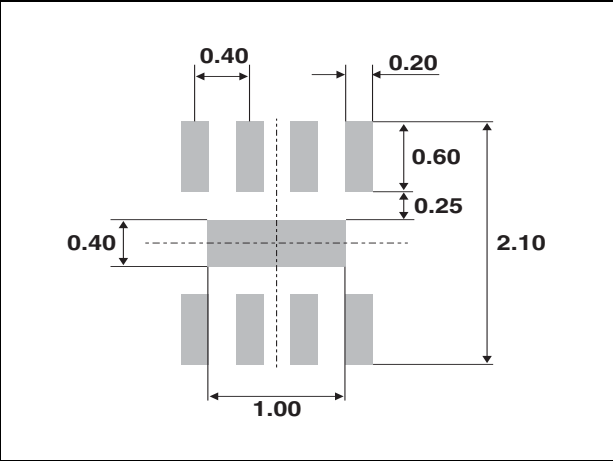


Figure 10. Marking

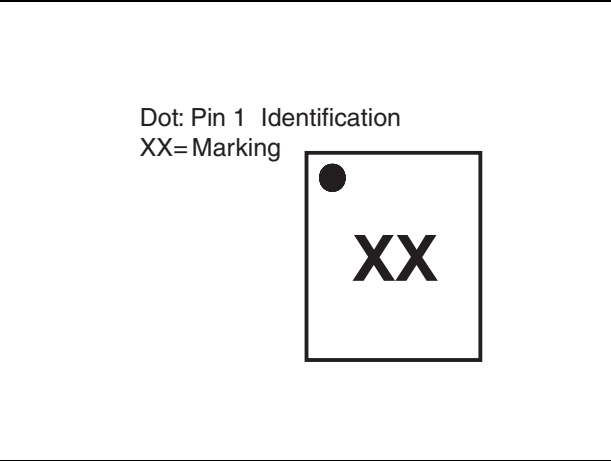
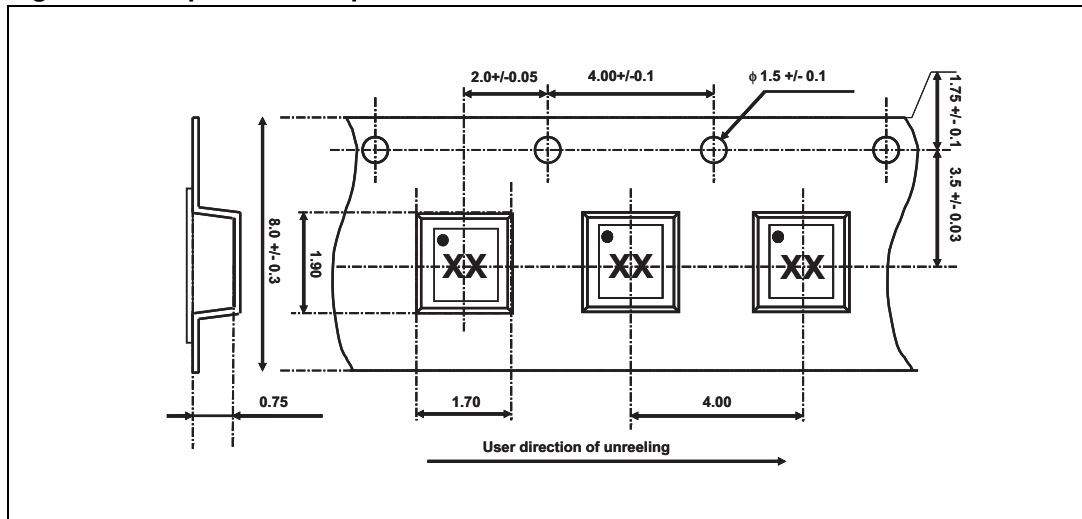


Figure 11. Tape and reel specification



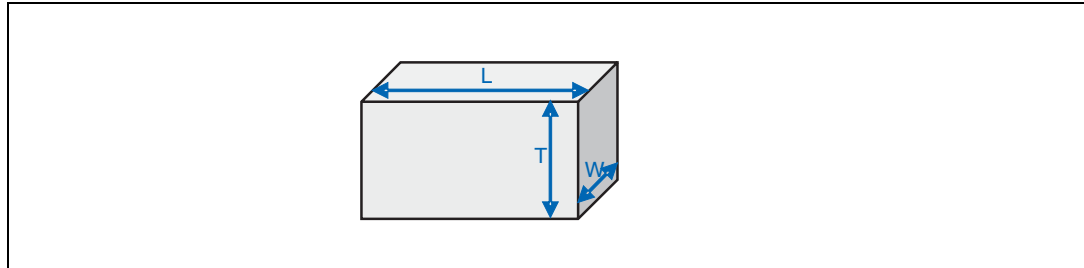
Note: Product marking may be rotated by 90° for assembly plant differentiation. In no case should this product marking be used to orient the component for its placement on a PCB. Only pin 1 mark is to be used for this purpose.

4 Recommendation on PCB assembly

4.1 Stencil opening design

1. General recommendation on stencil opening design
 - a) Stencil opening dimensions: L (Length), W (Width), T (Thickness).

Figure 12. Stencil opening dimensions



- b) General design rule

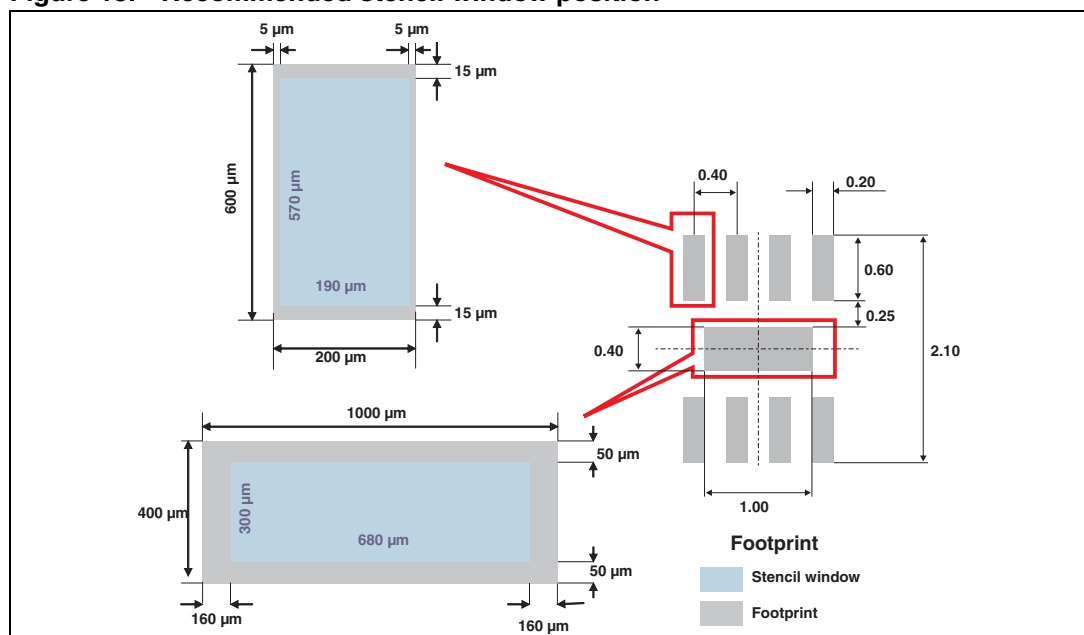
Stencil thickness (T) = 75 ~ 125 μm

$$\text{Aspect Ratio} = \frac{W}{T} \geq 1.5$$

$$\text{Aspect Area} = \frac{L \times W}{2T(L + W)} \geq 0.66$$

2. Reference design
 - a) Stencil opening thickness: 100 μm
 - b) Stencil opening for central exposed pad: Opening to footprint ratio is 50%.
 - c) Stencil opening for leads: Opening to footprint ratio is 90%.

Figure 13. Recommended stencil window position



4.2 Solder paste

1. Halide-free flux qualification ROL0 according to ANSI/J-STD-004.
2. “No clean” solder paste is recommended.
3. Offers a high tack force to resist component movement during high speed
4. Solder paste with fine particles: powder particle size is 20-45 μm .

4.3 Placement

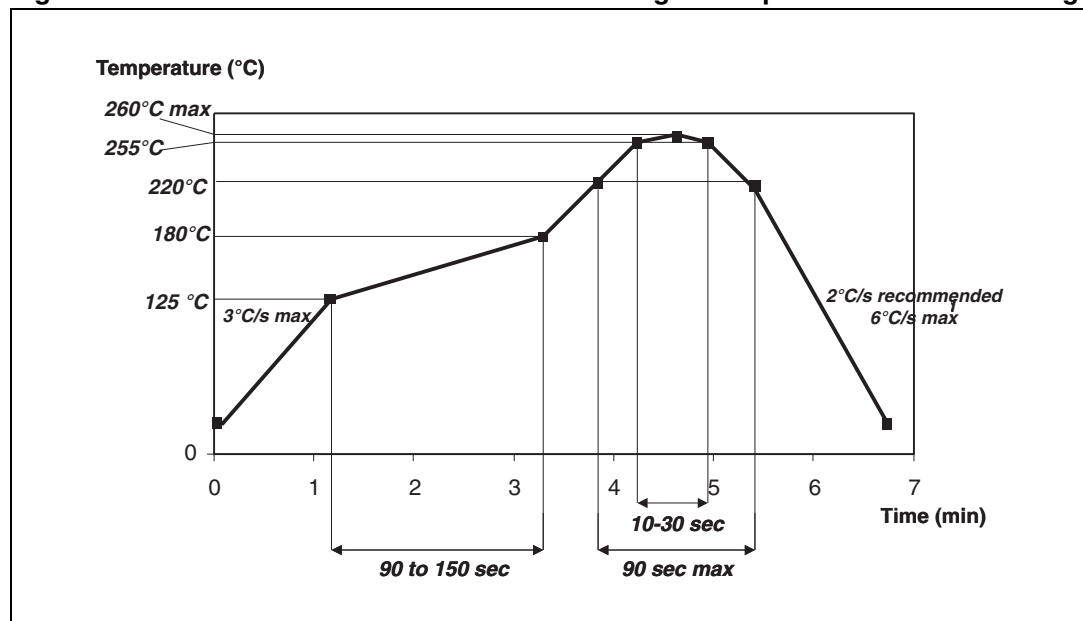
1. Manual positioning is not recommended.
2. It is recommended to use the lead recognition capabilities of the placement system, not the outline centering
3. Standard tolerance of ± 0.05 mm is recommended.
4. 3.5 N placement force is recommended. Too much placement force can lead to squeezed out solder paste and cause solder joints to short. Too low placement force can lead to insufficient contact between package and solder paste that could cause open solder joints or badly centered packages.
5. To improve the package placement accuracy, a bottom side optical control should be performed with a high resolution tool.
6. For assembly, a perfect supporting of the PCB (all the more on flexible PCB) is recommended during solder paste printing, pick and place and reflow soldering by using optimized tools.

4.4 PCB design preference

1. To control the solder paste amount, the closed via is recommended instead of open vias.
2. The position of tracks and open vias in the solder area should be well balanced. The symmetrical layout is recommended, in case any tilt phenomena caused by asymmetrical solder paste amount due to the solder flow away.

4.5 Reflow profile

Figure 14. ST ECOPACK® recommended soldering reflow profile for PCB mounting



Note: Minimize air convection currents in the reflow oven to avoid component movement.

5 Ordering information

Table 4. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
EMIF04-1502M8	G4 ⁽¹⁾	Micro QFN	4 mg	3000	Tape and reel (7")

1. The marking can be rotated by 90° to differentiate assembly location

6 Revision history

Table 5. Document revision history

Date	Revision	Changes
12-Dec-2005	1	Initial release.
03-Jul-2006	2	Reformatted to current standard. Changed Figure 1 to show improved results.
01-Feb-2007	3	Added note on marking rotation in section 3. Package information.
26-Feb-2007	4	Pins range corrected on Micro QFN bottom view picture on page 1.
04-Feb-2008	5	Reformatted to current standards. Updated ECOPACK statement. Updated Section 4: Recommendation on PCB assembly .
05-Jan-2009	6	Corrected graphic in Table 3 . Reformatted to current standards.

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